WHAT IS CLAIMED IS:

1. A transducer, comprising

a base mountable on a substrate, and

an input/output (I/O) lead configured to contact an I/O lead of an integrated circuit mounted on the substrate.

2. The transducer of claim 1, wherein the transducer I/O lead is configured to electrically connect to the integrated circuit I/O lead independently of any electrically conductive path of the substrate.

3. The transducer of claim 1, wherein the transducer I/O lead is configured to contact the integrated circuit I/O lead at a transducer surface substantially parallel to a mounting surface of the substrate.

4. The transducer of claim 1, wherein the transducer I/O lead is configured to contact a pin I/O lead of the integrated circuit.

5. The transducer of claim 1, wherein the transducer I/O lead is configured to contact a solder ball lead of the integrated circuit.

6. The transducer of claim 1, wherein the transducer I/O lead is configured to contact the integrated circuit I/O lead at a transducer surface adjacent to a mounting surface of the substrate.

7. The transducer of claim 1, further comprising a power input lead connectable to a power line of the substrate.

8. The transducer of claim 1, further comprising a transductional device.

9. The transducer of claim 1, wherein the transductional device is an opto-electronic device.

10. The transducer of claim 1, wherein the transductional device is an electronic device.

11. A method of connecting a transducer to an integrated circuit mounted on a substrate, comprising

mounting the transducer to the substrate, and

contacting an input/output (I/O) lead of the transducer to an I/O lead of the integrated circuit.

12. The method of claim 11, wherein the transducer I/O lead electrically connects to the integrated circuit I/O lead independently of any electrically conductive path of the substrate.

13. The method of claim 11, wherein the transducer I/O lead contacts the integrated circuit I/O lead at a transducer surface substantially parallel to a mounting surface of the substrate.

14. The method of claim 11, wherein the transducer I/O lead contacts a pin I/O lead of the integrated circuit.

15. The method of claim 11, wherein the transducer I/O lead contacts a solder ball lead of the integrated circuit.

16. The method of claim 11, wherein the transducer I/O lead contacts the integrated circuit I/O lead at a transducer surface adjacent to a mounting surface of the substrate.

17. The method of claim 11, wherein the transducer connects to a power line of the substrate when the transducer is mounted to the substrate.

18. A system, comprising

a substrate,

an integrated circuit mounted on the substrate and having an input/output (I/O) lead, and

a transducer having an I/O lead configured to contact the I/O lead of the integrated circuit.

19. The system of claim 18, wherein the transducer I/O lead is configured to electrically connect to the integrated circuit I/O lead independently of any electrically conductive path of the substrate.